

# TITANIUM ALUMINIUM / VANADIUM Sputtering Target

**NS6130-10-1061**

## Quick Facts

Product	:	Titanium Aluminium Vanadium Sputtering Target
Stock No	:	NS6130-10-1061
CAS	:	12743-70-3
Molecular Formula	:	TiAlV
Form	:	Solid

## Technical Specification

Diameter	Thickness	Purity
50.8 mm ± 1mm	3 mm ± 0.5mm	99.99%

A titanium aluminum vanadium (Ti-Al-V) sputtering target is used in PVD processes to deposit thin films onto silicon wafers by bombarding the target with high-energy particles. It serves in semiconductor devices, microelectronics, photovoltaics, wear-resistant coatings, aerospace components, biocompatible medical device coatings, and optical coatings for lenses and mirrors due to its strength, corrosion resistance, and thermal stability.

### Applications:

- Thin Film Deposition
- Coatings
- Aerospace
- Biomedical
- Optical Applications

\* This image is for graphic purposes only and does not represent the actual product.

